

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kosei YAMASHITA</td> <td>05/28/2007</td> </tr> <tr> <td>Yasushi MIYAJIMA</td> <td>05/30/2007</td> </tr> <tr> <td>Motoyuki TAKAI</td> <td>05/31/2007</td> </tr> <tr> <td>Yoichiro SAKO</td> <td>06/05/2007</td> </tr> <tr> <td>Toshiro TERAUCHI</td> <td>05/25/2007</td> </tr> <tr> <td>Toru SASAKI</td> <td>06/07/2007</td> </tr> </tbody> </table>		Name	Execution Date	Kosei YAMASHITA	05/28/2007	Yasushi MIYAJIMA	05/30/2007	Motoyuki TAKAI	05/31/2007	Yoichiro SAKO	06/05/2007	Toshiro TERAUCHI	05/25/2007	Toru SASAKI	06/07/2007
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Toru SASAKI	06/07/2007														
RECEIVING PARTY DATA															
Name:	SONY CORPORATION														
Street Address:	1-7-1 Konan, Minato-ku														
City:	Tokyo														
State/Country:	Japan														
Postal Code:	108-0075														
PROPERTY NUMBERS Total: 1															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11721759</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11721759										
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Application Number:	11721759														
CORRESPONDENCE DATA															
Fax Number:	(703)413-2220														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
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Correspondent Name:	Oblon, Spivak, et al.														
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ATTORNEY DOCKET NUMBER:	308716US8PCT														
NAME OF SUBMITTER:	Emebet Girma														

OP \$40.00 11721759

Total Attachments: 6

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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
MUSIC COMPOSITION DATA RECONSTRUCTION DEVICE, MUSIC COMPOSITION DATA RECONSTRUCTION METHOD, MUSIC CONTENT REPRODUCTION DEVICE, AND MUSIC CONTENT REPRODUCTION METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, 108-0075 Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 11/721,759
Filing Date: June 14, 2007

This assignment executed on the dates indicated below.

Kosei YAMASHITA

Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Kosei Yamashita

May 28, 2007

Signature of first or sole inventor

Date of this assignment

Yasushi MIYAJIMA

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Yasushi Miyajima

May 30, 2007

Signature of second inventor

Date of this assignment

Motoyuki TAKAI

Name of third inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Motoyuki Takai

May 31, 2007

Signature of third inventor

Date of this assignment

Yoichiro SAKO

Name of fourth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fourth inventor

Yoichiro Sako

June 5, 2007

Signature of fourth inventor

Date of this assignment

Toshiro TERAUCHI

Name of fifth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

Toru SASAKI

Name of sixth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of sixth inventor

Toru Sasaki

June 7, 2007

Signature of sixth inventor

Date of this assignment

PATENT

REEL: 019450 FRAME: 0314

Yuichi SAKAI

Name of seventh inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of seventh inventor

Yuichi Sakai

June 7, 2007

Signature of seventh inventor

Date of this assignment

ASSIGNMENT

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And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

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Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

Yasushi MIYAJIMA

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Signature of second inventor

Date of this assignment

Motoyuki TAKAI

Name of third inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Signature of third inventor

Date of this assignment

Yoichiro SAKO

Name of fourth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Toshiro TERAUCHI

Name of fifth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fifth inventor

Signature of fifth inventor

May 25, 2007

Date of this assignment

Toru SASAKI

Name of sixth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of sixth inventor

Signature of sixth inventor

Date of this assignment

Yuichi SAKAI

Name of seventh inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of seventh inventor

Signature of seventh inventor

Date of this assignment